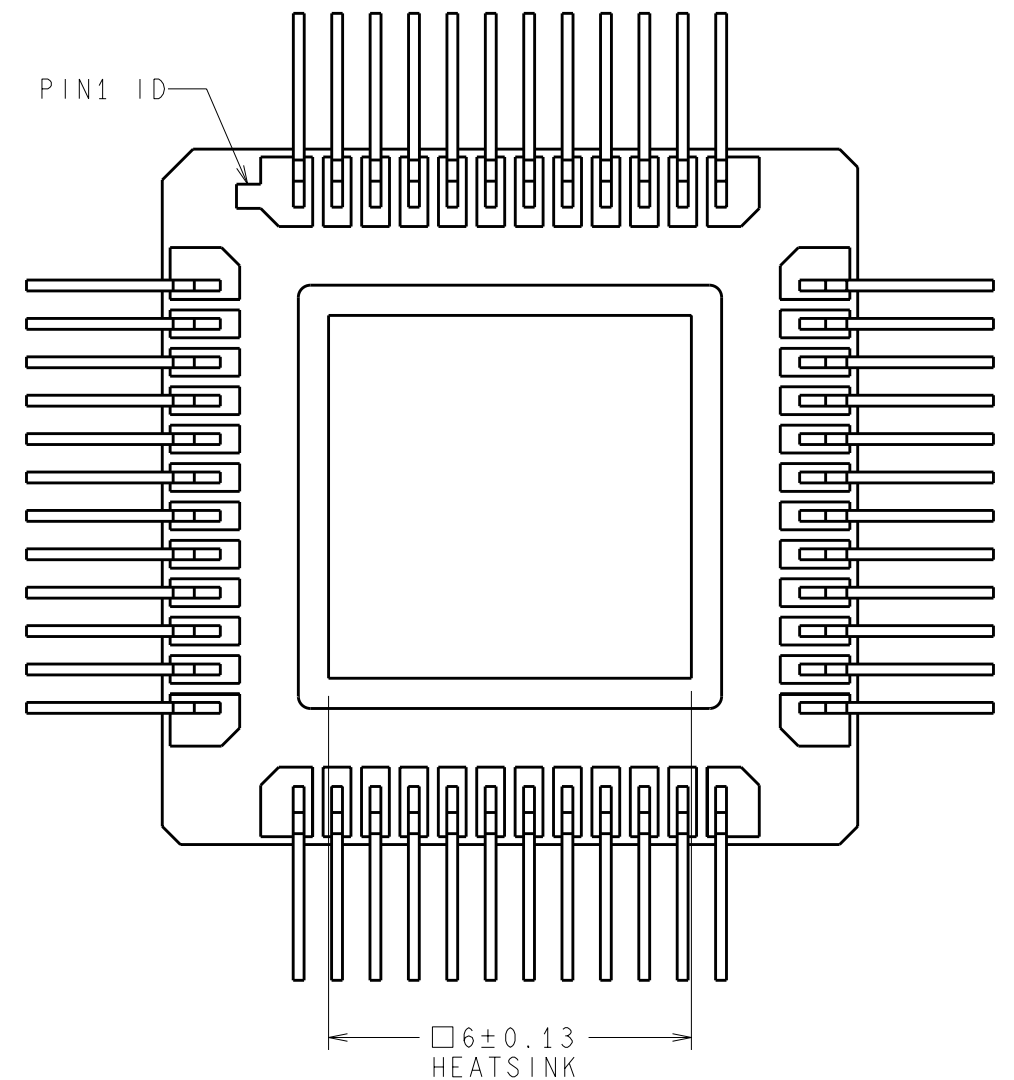
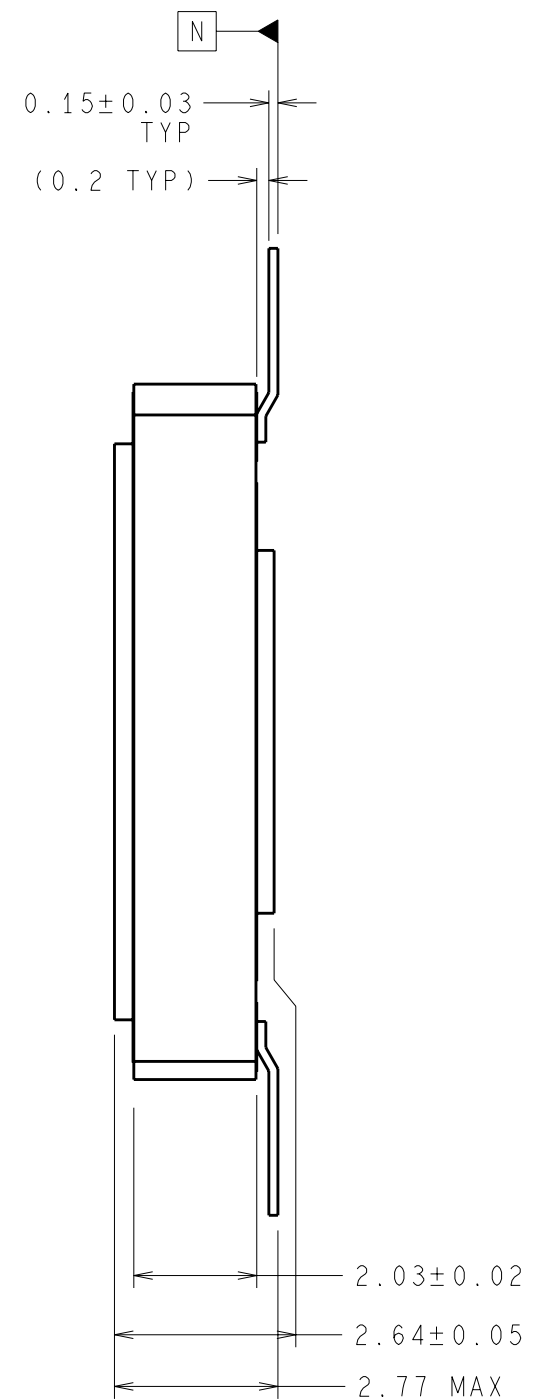
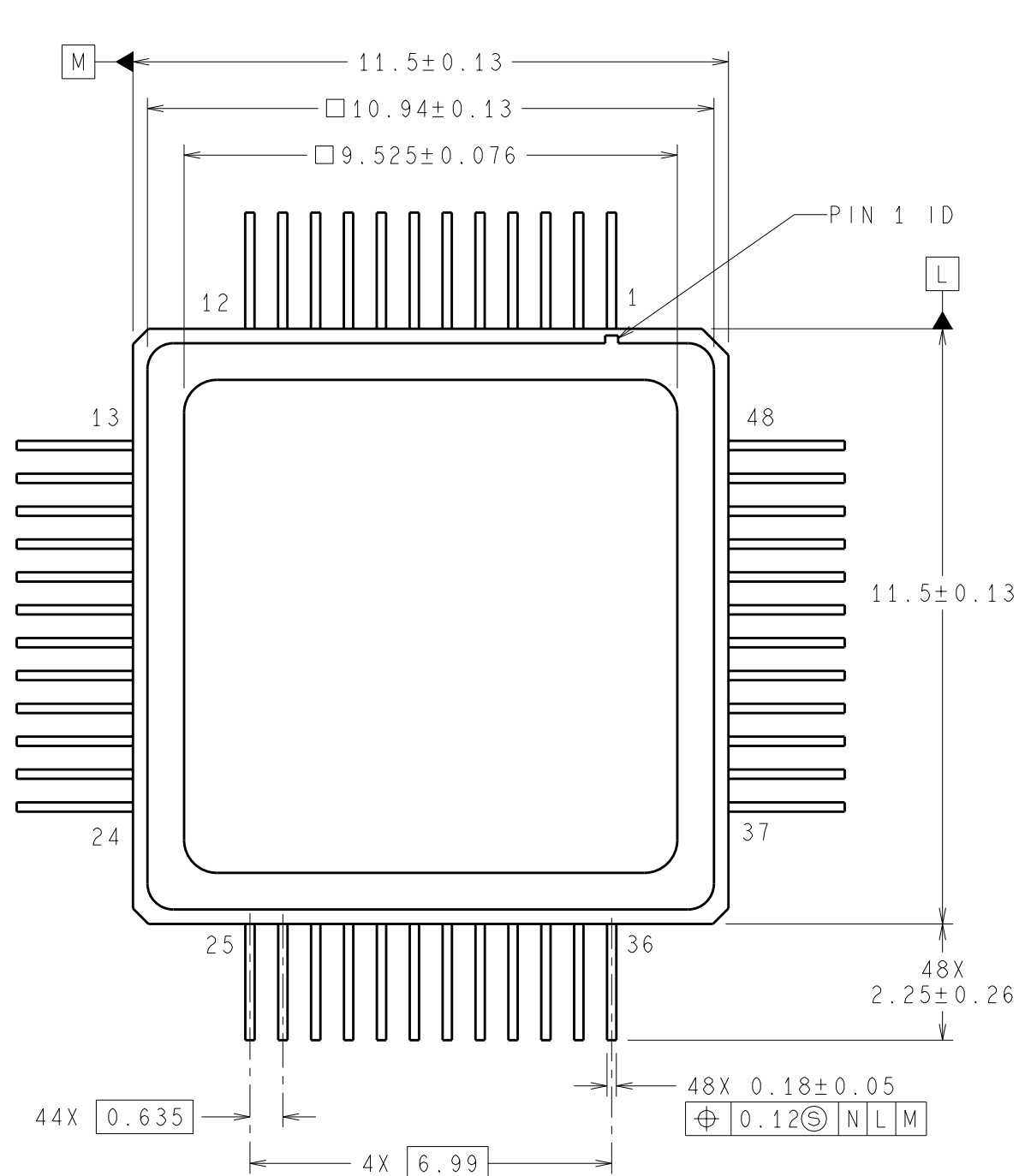


REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	2179	11/28/2006	TL/JL
B	REVISE NOTE 2 & UPDATE NOTE 4.	2272	04/24/2007	MS/JL



NOTES: UNLESS OTHERWISE SPECIFIED

- FOR SOLDER THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE ([www.national.com](http://www.national.com)).
- ALL EXPOSED METAL AND METALIZED AREAS TO BE GOLD PLATED 120 TO 225 MICRONS/ 3.05 TO 5.72 MICROMETERS OVER 120 TO 350 MICRONS/ 3.05 TO 8.89 MICROMETERS NICKEL PLATE.
- LEAD THICKNESS AND WIDTH APPLY TO BASE METAL.
- NO JEDEC REGISTRATION AS OF APRIL 2007.

**DIMENSIONS ARE IN MILLIMETERS**  
VALUES IN ( ) FOR REFERENCE ONLY

**MIL-PRF-38535**  
**CONFIGURATION CONTROL**

APPROVALS		DATE	 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090
DRAWN	T. LEQUANG	11/28/2006	
DFTG. CHK.	THANH LEQUANG	04/24/2007	
ENGR. CHK.	JOE LUNDY	04/24/2007	
PROJECTION  MM			<b>CQFP,</b> <b>11.5x11.5x2.64mm,</b> <b>48 LEAD, 0.635mm PITCH</b>
SCALE	SIZE	DRAWING NUMBER	REV
NTS	B	(SC)MKT-EL48A	B
FORMERLY: N/A			SHEET 1 of 1